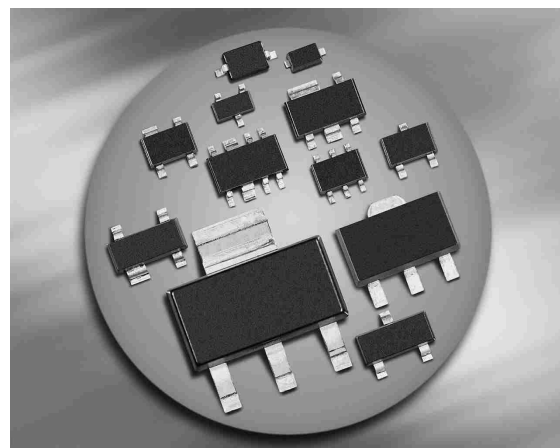


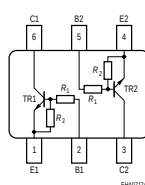
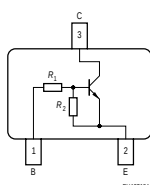
NPN Silicon Digital Transistor

- Switching circuit, inverter, interface circuit driver circuit
- Built in bias resistor ($R_1=47\text{ k}\Omega$, $R_2=47\text{ k}\Omega$)
- BCR148S: Two internally isolated transistors with good matching in one multichip package
- BCR148S: For orientation in reel see package information below
- Pb-free (RoHS compliant) package ¹⁾
- Qualified according AEC Q101



BCR148/F
BCR148W

BCR148S



Type	Marking	Pin Configuration						Package
BCR148	WEs	1=B	2=E	3=C	-	-	-	SOT23
BCR148F	WEs	1=B	2=E	3=C	-	-	-	TSFP-3
BCR148S	WEs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SOT363
BCR148W	WEs	1=B	2=E	3=C	-	-	-	SOT323

¹⁾Pb-containing package may be available upon special request

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	50	V
Collector-base voltage	V_{CBO}	50	
Input forward voltage	$V_{i(fwd)}$	80	
Input reverse voltage	$V_{i(rev)}$	10	
Collector current	I_C	100	mA
Total power dissipation- BCR148, $T_S \leq 102^\circ\text{C}$ BCR148F, $T_S \leq 128^\circ\text{C}$ BCR148S, $T_S \leq 115^\circ\text{C}$ BCR148W, $T_S \leq 124^\circ\text{C}$	P_{tot}	200 250 250 250	mW
Junction temperature	T_j	150	
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾ BCR148 BCR148F BCR148S BCR148W	R_{thJS}	≤ 240 ≤ 90 ≤ 140 ≤ 105	K/W

¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

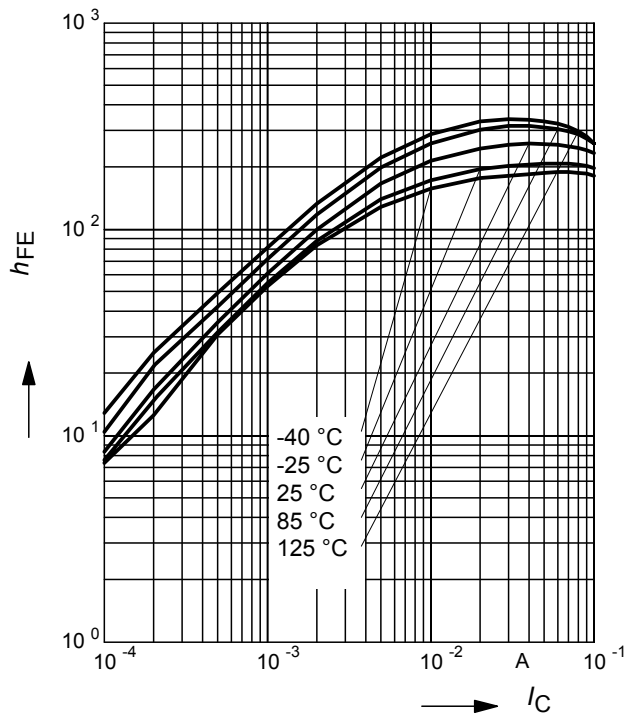
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 100\ \mu\text{A}$, $I_B = 0$	$V_{(\text{BR})\text{CEO}}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10\ \mu\text{A}$, $I_E = 0$	$V_{(\text{BR})\text{CBO}}$	50	-	-	
Collector-base cutoff current $V_{\text{CB}} = 40\ \text{V}$, $I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{\text{EB}} = 10\ \text{V}$, $I_C = 0$	I_{EBO}	-	-	164	μA
DC current gain ¹⁾ $I_C = 5\ \text{mA}$, $V_{\text{CE}} = 5\ \text{V}$	h_{FE}	70	-	-	-
Collector-emitter saturation voltage ¹⁾ $I_C = 10\ \text{mA}$, $I_B = 0.5\ \text{mA}$	V_{CEsat}	-	-	0.3	V
Input off voltage $I_C = 100\ \mu\text{A}$, $V_{\text{CE}} = 5\ \text{V}$	$V_{\text{i(off)}}$	0.8	-	1.5	
Input on voltage $I_C = 2\ \text{mA}$, $V_{\text{CE}} = 0.3\ \text{V}$	$V_{\text{i(on)}}$	1	-	3	
Input resistor	R_1	32	47	62	k Ω
Resistor ratio	R_1/R_2	0.9	1	1.1	-
AC Characteristics					
Transition frequency $I_C = 10\ \text{mA}$, $V_{\text{CE}} = 5\ \text{V}$, $f = 100\ \text{MHz}$	f_{T}	-	100	-	MHz
Collector-base capacitance $V_{\text{CB}} = 10\ \text{V}$, $f = 1\ \text{MHz}$	C_{cb}	-	3	-	pF

¹⁾Pulse test: $t < 300\ \mu\text{s}$; $D < 2\%$

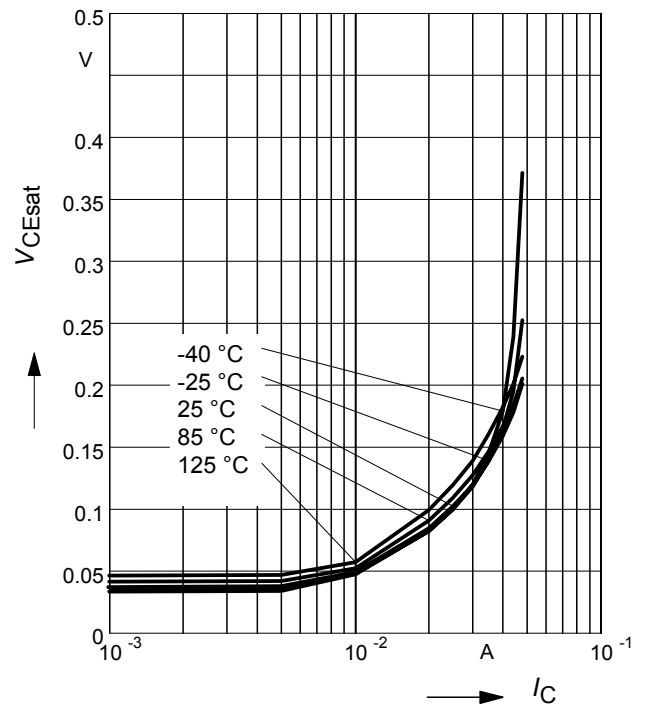
DC current gain $h_{FE} = f(I_C)$

$V_{CE} = 5V$ (common emitter configuration)



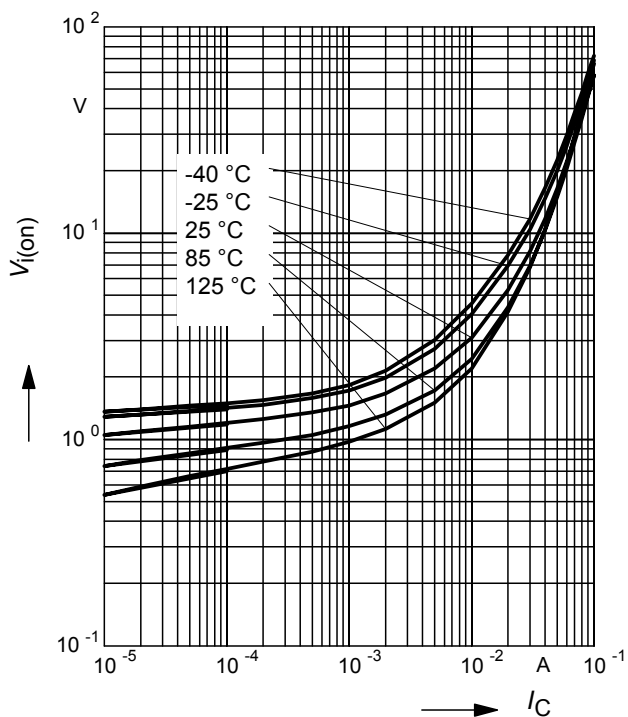
Collector-emitter saturation voltage

$V_{CEsat} = f(I_C)$, $I_C/I_B = 20$



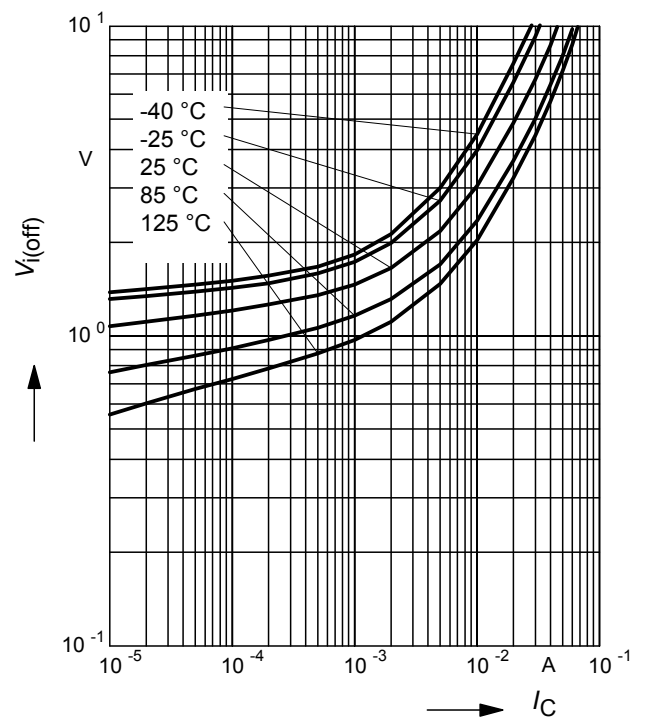
Input on Voltage $V_{i(on)} = f(I_C)$

$V_{CE} = 0.3V$ (common emitter configuration)



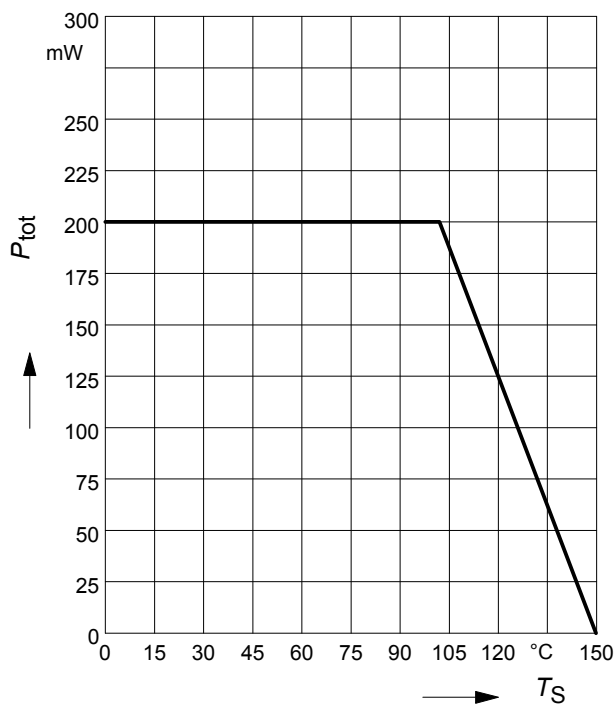
Input off voltage $V_{i(off)} = f(I_C)$

$V_{CE} = 5V$ (common emitter configuration)



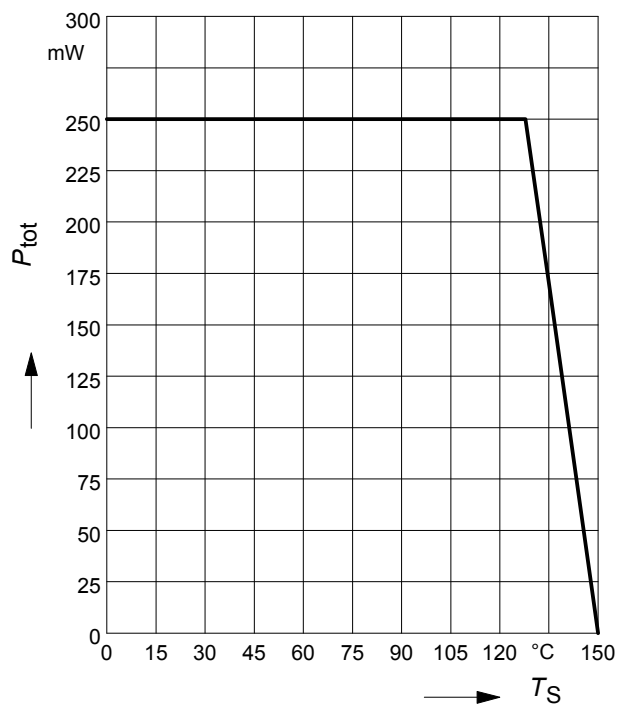
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR148



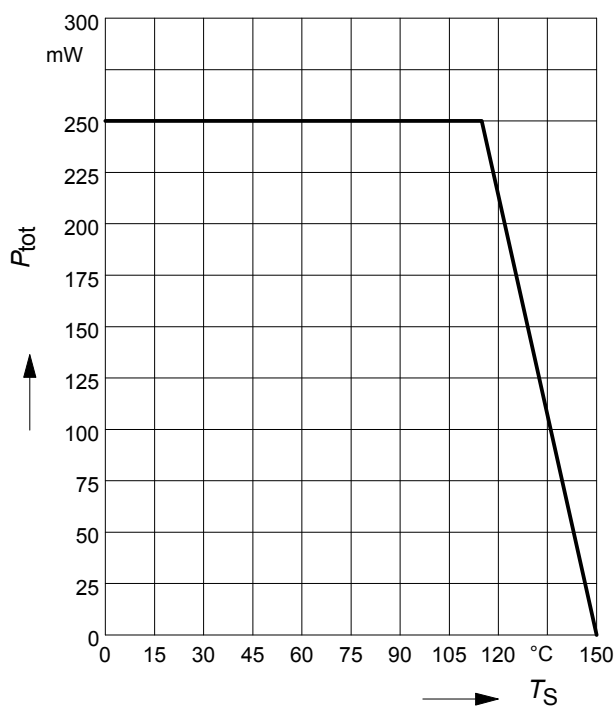
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR148F



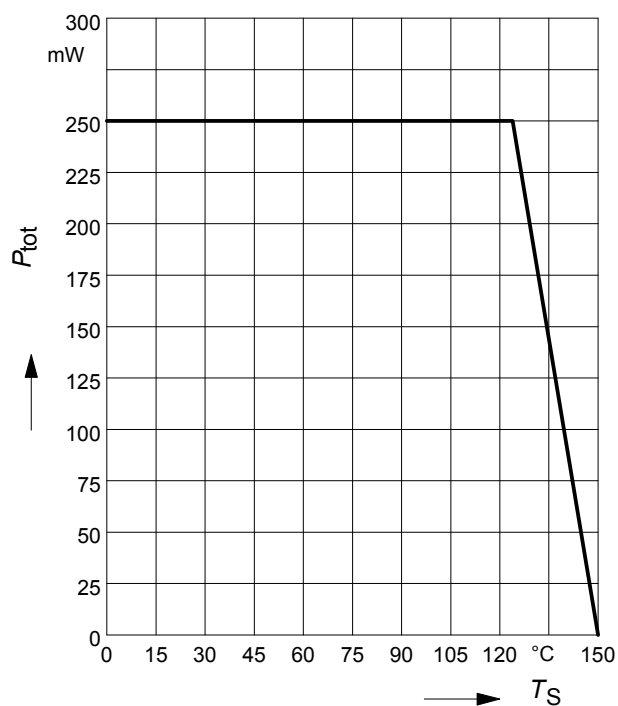
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR148S



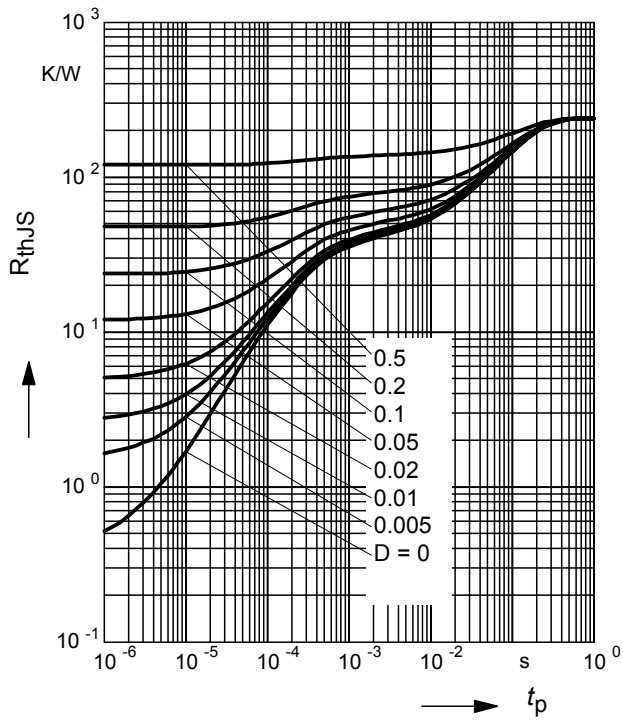
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR148W



Permissible Pulse Load $R_{thJS} = f(t_p)$

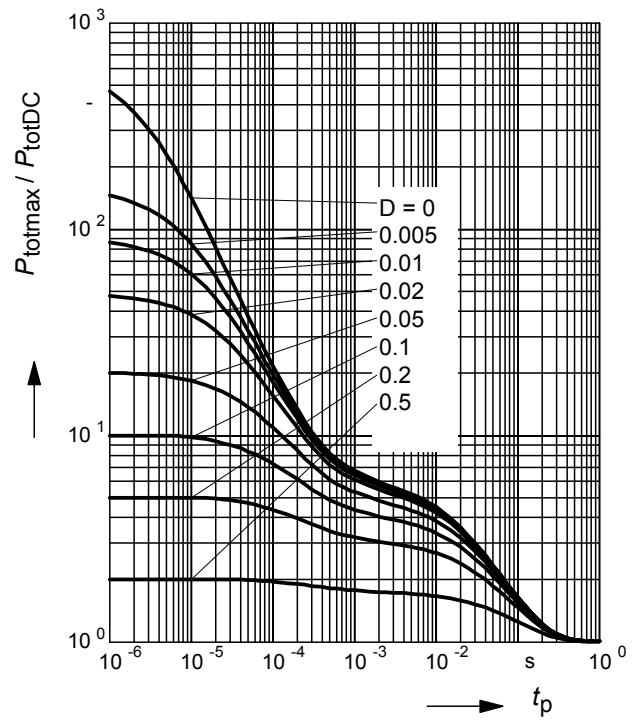
BCR148



Permissible Pulse Load

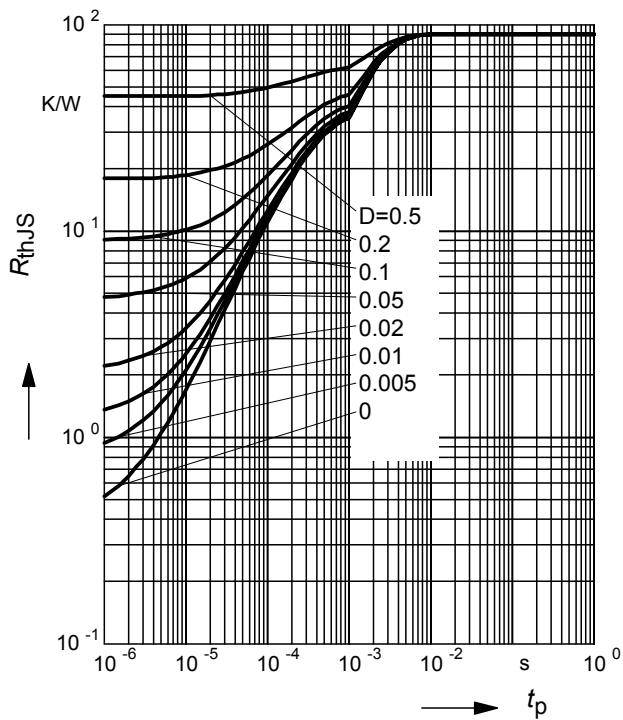
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR148



Permissible Puls Load $R_{thJS} = f(t_p)$

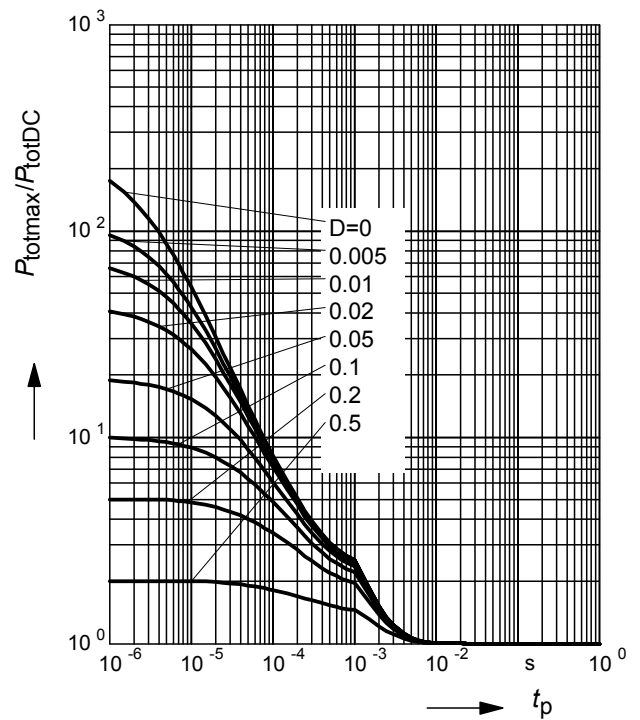
BCR148F



Permissible Pulse Load

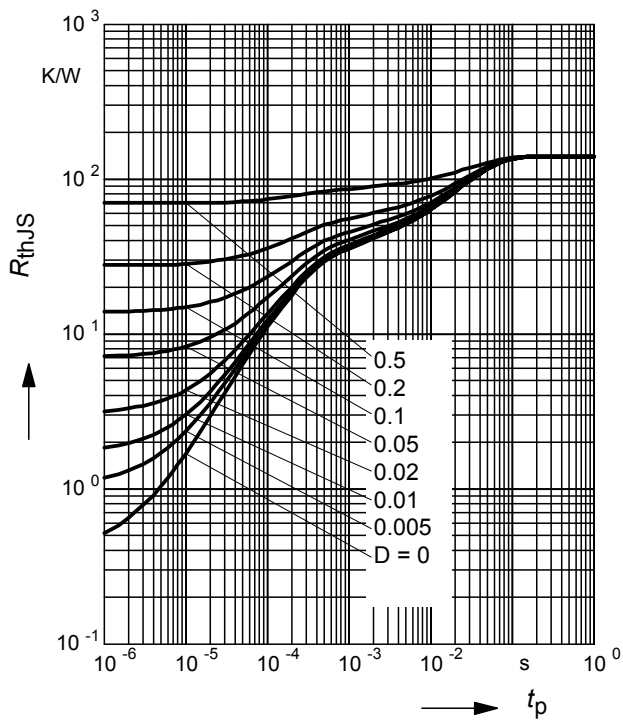
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR148F



Permissible Puls Load $R_{thJS} = f(t_p)$

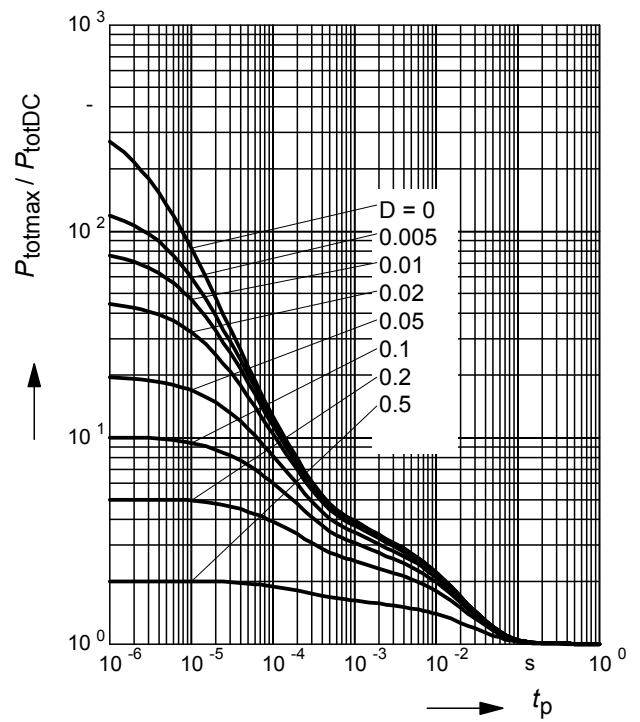
BCR148S



Permissible Pulse Load

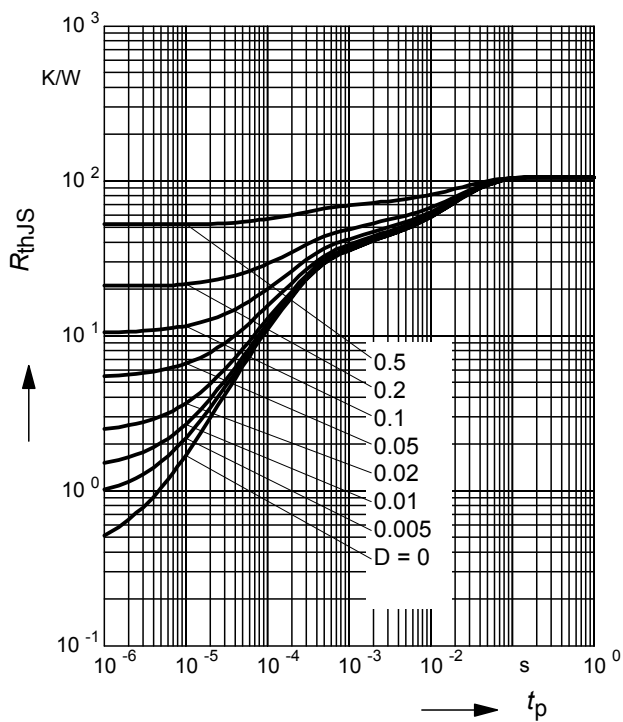
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR148S



Permissible Puls Load $R_{thJS} = f(t_p)$

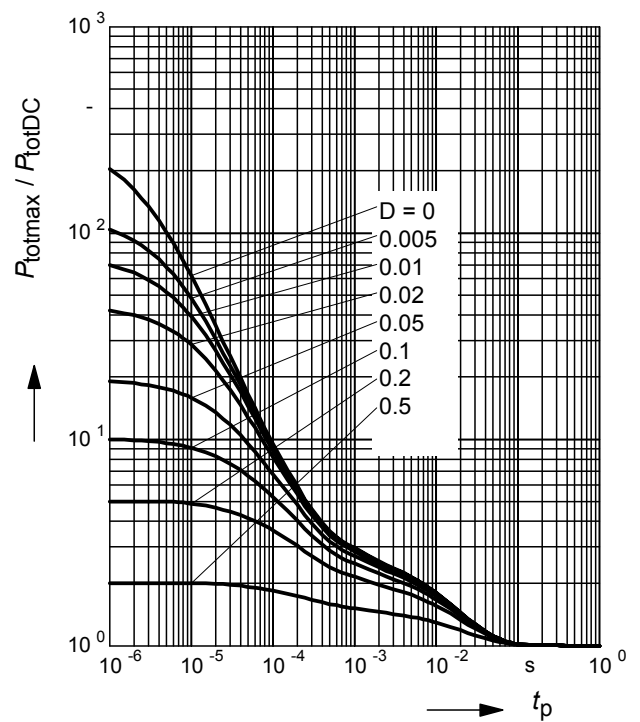
BCR148W

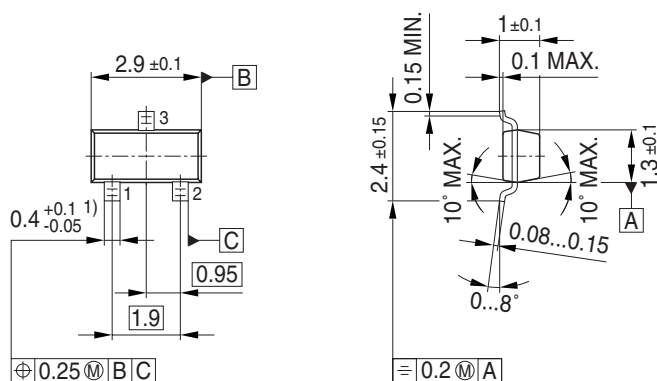


Permissible Pulse Load

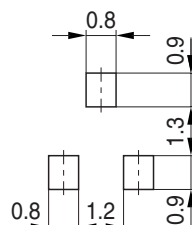
$$P_{totmax}/P_{totDC} = f(t_p)$$

BCR148W



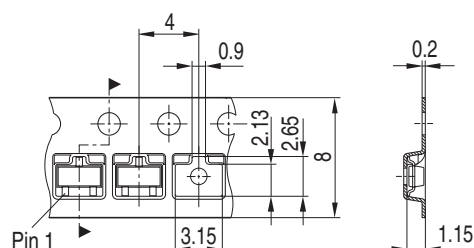


Foot Print

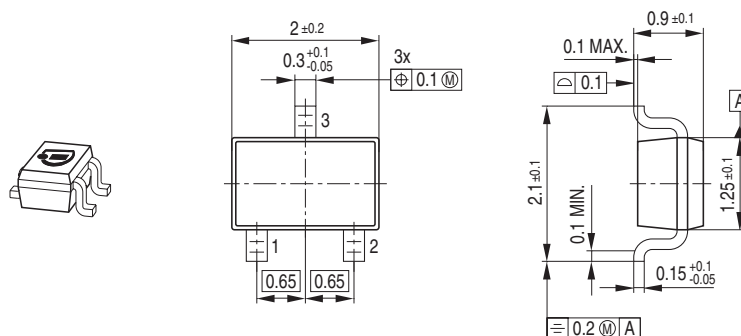


The diagram shows a top-down view of a BCW66 LED package. It is a rectangular component with four pins. The top pin is labeled 'Pin 1'. The package has a central rectangular area containing the text 'EHS' and '65'. To the right of this area, the text '2005, June' and 'Date code (YM)' is shown. Above the package, the Infineon logo and the text 'Manufacturer' are displayed. Below the package, the text 'BCW66' and 'Type code' are shown.

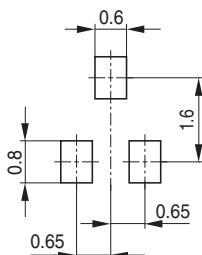
Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



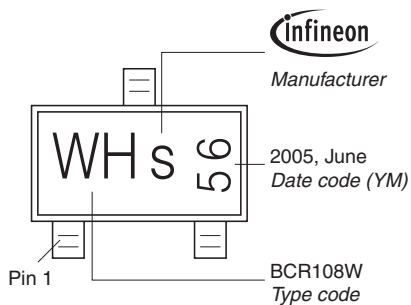
Package Outline



Foot Print

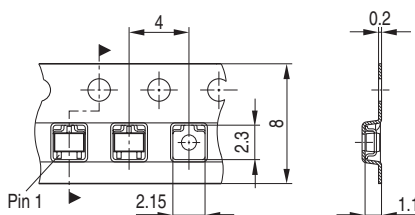


Marking Layout (Example)



Standard Packing

Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel



Technical drawing of a 2x3 grid of rectangular features. The drawing shows a top-down view with a dashed center line. Dimensions are indicated as follows: a horizontal dimension of 0.3 between the centers of the top two rectangles; a vertical dimension of 0.7 between the top and bottom edges of the top row; a vertical dimension of 0.9 between the top and bottom edges of the bottom row; a horizontal dimension of 0.65 from the left edge to the center line; and a horizontal dimension of 0.65 from the center line to the right edge. A vertical dimension of 1.6 is shown on the right side, spanning the height of both rows.

Infineon
technologies

Manufacturer

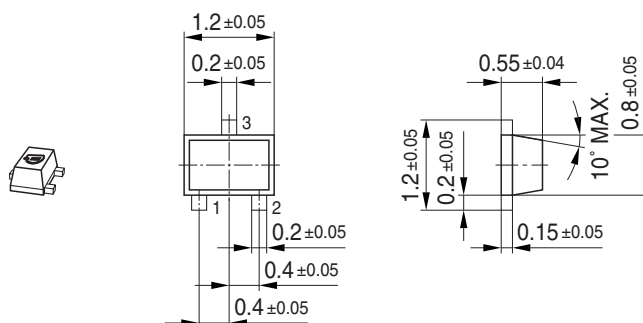
2005, June
Date code (Year/Month)

Pin 1 marking
Laser marking

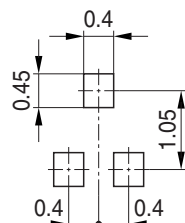
BCR108S
Type code

The technical drawing shows a top-down view of a rectangular PCB footprint with irregular edges. Key features include:
 - A horizontal dimension of 4 units across the top.
 - A vertical dimension of 8 units along the right side.
 - Three square pads arranged horizontally, each with a diameter of 2.3 units.
 - The distance between the center of the first and second pad is 2.15 units.
 - A circular feature is located to the right of the pads.
 - A "Pin 1" marking points to the left edge of the first square pad.
 - A cross-sectional view on the right shows a thickness of 0.2 units and a mounting height or clearance of 1.1 units.

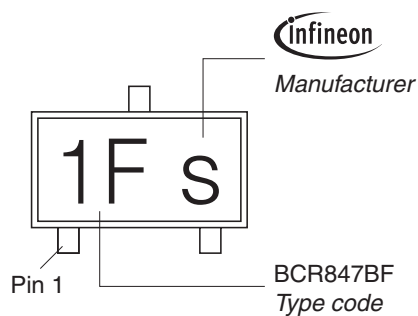
Package Outline



Foot Print

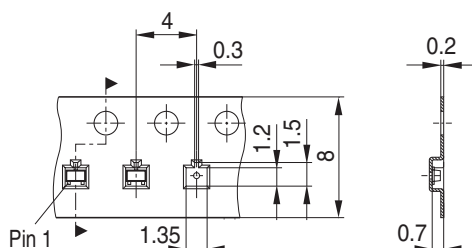


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel



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